

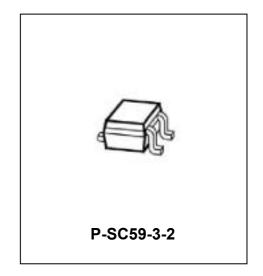
# **High Precision Hall-Effect Switch**

TLE4976-1H

Data Sheet Version 1.0 2003-11-20

#### **Features**

- 2-wire current interface 6/14 mA
- 3.0V to 24V supply voltage operation
- Operation from unregulated power supply
- High sensitivity and high stability of the magnetic switching points
- High resistance to mechanical stress by Active Error Compensation
- Reverse battery protection (-18V)
- Superior temperature stability
- Peak temperatures up to 195°C without damage
- Low jitter (typ. 1μs)
- High ESD performance (±8kV HBM)
- Digital output signal
- Unipolar version
- SMD package P-SC59-3-2 (SOT-23 compatible)



Туре	Ordering Code	Package
TLE4976-1H	Q62705K0710	P-SC59-3-2

## **Functional Description**

The TLE4976-1H is an integrated circuit Hall-effect sensor designed specifically for highly accurate applications with a current interface. Precise magnetic switching points and high temperature stability are achieved by active compensation circuits and chopper techniques on chip.



### **Circuit Description**

The chopped Hall IC Switch comprises a Hall probe, bias generator, compensation circuits, oscillator, and a current output.

The bias generator provides currents for the Hall probe and the active circuits. Compensation circuits stabilize the temperature behavior and reduce technology variations.

The Active Error Compensation rejects offsets in signal stages and the influence of mechanical stress to the Hall probe caused by molding and soldering processes and other thermal stresses in the package. This chopper technique together with the threshold generator and the comparator ensures high accurate magnetic switching points.

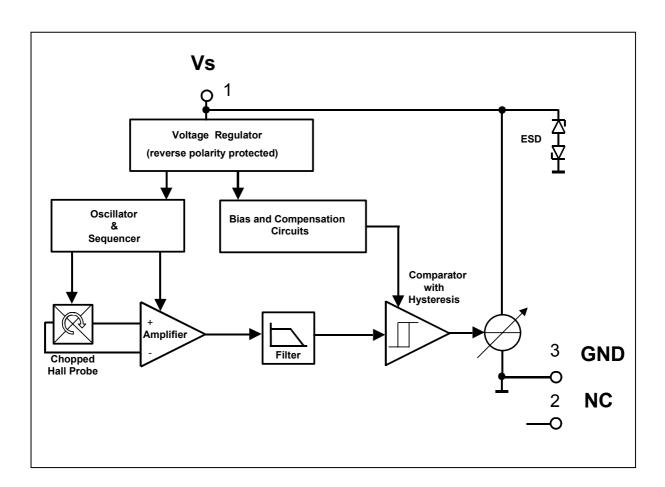


Figure 1 Block Diagram



# **Pin Configuration**

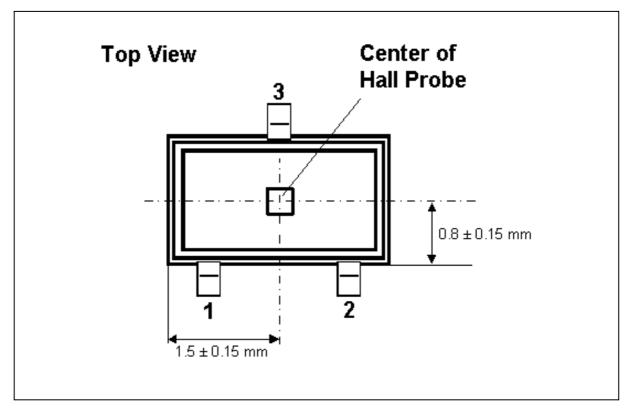


Figure 2: Pin Configuration (SOT-23 pin compatible)

## **Pin Definition and Functions**

Pin	Symbol	Function					
1	V <sub>S</sub>	Supply voltage					
2	NC	No internal connection					
3	GND	Ground					



# **Absolute Maximum Ratings**

 $Tj = -40 \text{ to } 150^{\circ}\text{C}$ 

Parameter	Symbol	min.	max.	Unit	Conditions
Supply Voltage	Vs	-18	18	V	
		-18	24		for 1h ( $R_S+R_L > 75$ Ohm)
		-18	26		for 5min (R <sub>S</sub> +R <sub>L</sub> > 75 Ohm)
Supply Current through protection device	ls	-50	+50	mA	
Junction Temperature	T <sub>i</sub>	-	155	°C	for 2000 h (not additive)
·	,		165		for 1000 h (not additive)
			175		for 168 h (not additive)
			195		for 3x1 h (additive)
Storage Temperature	Ts	-40	150	°C	
Magnetic Flux Density	В	-	unlimit.	mT	

Note: Stresses above those listed here may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ESD Protection**

Human Body Model (HBM) tests according to:

EOS/ESD Association Standard S5.1-1993 and Mil. Std. 883D method 3015.7

Parameter	Symbol	max.	Unit Conditions	
ESD Voltage	$V_{ESD}$	± 8	kV HBM, R= 1.500 Ohm,	
				C= 100pF; T <sub>A</sub> = 25°C

## **Operating Range**

Parameter	Symbol	min.	typ.	max.	Unit	Conditions
Supply Voltage	Vs	3.0	-	18	V	
		3.0		24		for 5min ( $R_S+R_L > 100 \text{ Ohm}$ )
Junction Temperature	T <sub>i</sub>	-40	-	150	°C	
·	,			175		for 168 h



### **AC/DC Characteristics**

over operating range, unless otherwise specified. Typical values correspond to  $V_S$ =12V and  $T_A$ =25°C.

Parameter	Symbol	min.	typ.	max.	Unit	Conditions
Supply Current low	I <sub>Slow</sub>	5	6	7	mA	B <brp; v<sub="">S = 3.0V 18V</brp;>
Supply Current high	I <sub>Shigh</sub>	12	14	17	mA	B>Bop; V <sub>S</sub> = 3.0V 18V
Reverse Current	I <sub>SR</sub>	0	-	0.2	mA	V <sub>S</sub> = -18V
Output Fall Time	t <sub>f</sub>		0.4	1.6	μs	R <sub>S</sub> = 100 Ohm; Figure 3
Output Rise Time	t <sub>r</sub>		0.4	1.6	μs	R <sub>S</sub> = 100 Ohm; Figure 3
Chopper Frequency	f <sub>OSC</sub>	-	320	-	kHz	
Switching Frequency	f <sub>SW</sub>	0	-	15 <sup>1)</sup>	kHz	
Delay Time <sup>2)</sup>	$t_d$	1	13	-	μs	
Output Jitter <sup>3)</sup>	t <sub>QJ</sub>	-	1	-	µs <sub>RMS</sub>	Typ. Value for Square-Wave
						Signal 1kHz
Repeatability of magnetic	B <sub>REP</sub>	-	40	-	$\mu T_{RMS}$	Typ. Value for
thresholds <sup>4)</sup>						ΔB/Δt>12mT/ms
Power-On Time <sup>5)</sup>	t <sub>PON</sub>	-	13	-	μs	V <sub>S</sub> >= 3.0V
Thermal Resistance <sup>6)</sup>	$R_{thJA}$	-	100	-	K/W	
P-SC59-3-2						

<sup>1)</sup> To operate the sensor at the max. switching frequency, the value of the magnetic signal amplitude must be 1.4 times higher than for static fields. This is due to the -3dB corner frequency of the low pass filter in the signal path.

### **Magnetic Characteristics**

over operating range, unless otherwise specified. Typical values correspond to  $V_S$ =12V.

Parameter	Symbol	Tj [°C]	min.	typ.	max.	Unit	Conditions
Operate Point	B <sub>OP</sub>					mT	
TLE4976-1H		-40	5.5	9.25	11.0		
		25	5.5	9.25	11.0		
		150	5.5	9.25	11.0		
Release Point	$B_RP$					mT	
TLE4976-1H		-40	5.0	7.25	10.5		
		25	5.0	7.25	10.5		
		150	5.0	7.25	10.5		
Hysteresis	B <sub>HYS</sub>					mT	
TLE4976-1H		-40	0.5	2.0	3.0		
		25	0.5	2.0	3.0		
		150	0.5	2.0	3.0		
Temperature	TC					ppm/°C	
Compensation of		-	-	0	-		
Magnetic Thresholds							

Positive magnetic fields related with south pole of magnet to the branded side of package. Note: Typical characteristics specify mean values expected over the production spread.

<sup>2)</sup> Systematic delay between magnetic threshold reached and output switching.

<sup>&</sup>lt;sup>3)</sup> Jitter is the unpredictable deviation of the output switching delay.

B<sub>REP</sub> is equivalent to the noise constant.

Time from applying  $V_S >= 3.0 \text{ V}$  to the sensor until the output state is valid.

<sup>&</sup>lt;sup>6)</sup> Thermal resistance from junction to ambient. e.g.:  $V_s$ =12.0 V,  $R_s$ =100 Ohms,  $I_{Shigh\_typ}$ =14 mA => Power Dissipation  $P_{dis}$ =148.4 mW. In  $T_A$  =  $T_j$  – ( $R_{thJA}$  \*  $P_{dis}$ ) = 175 °C – (100 K/W \* 0.1484 W) =>  $T_A$  = 160.1 °C



# **Timing Diagram**

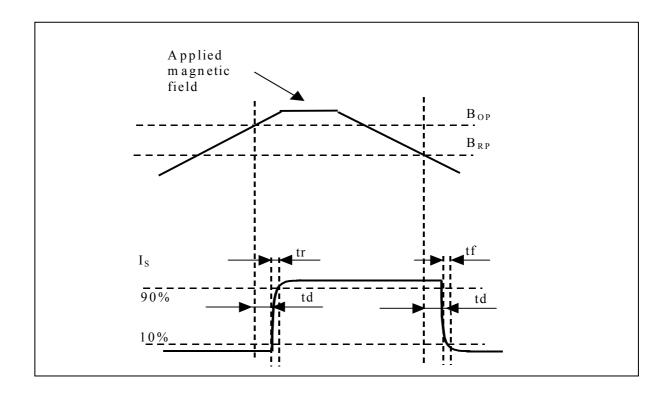


Figure 3: Timing Definition

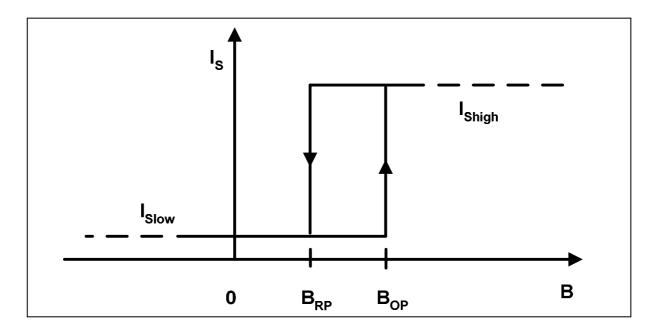


Figure 4: Output Signal



# **Package Dimensions**

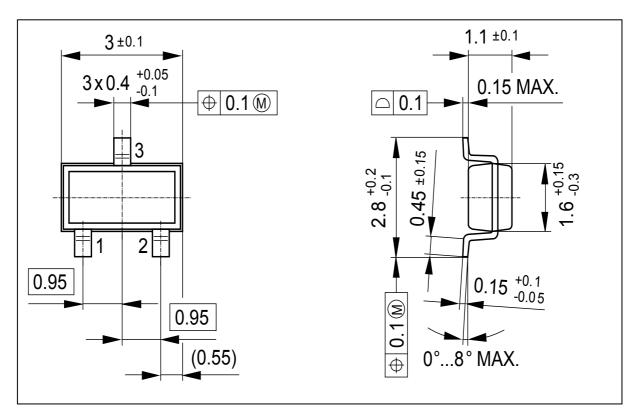


Figure 5: Package Dimension

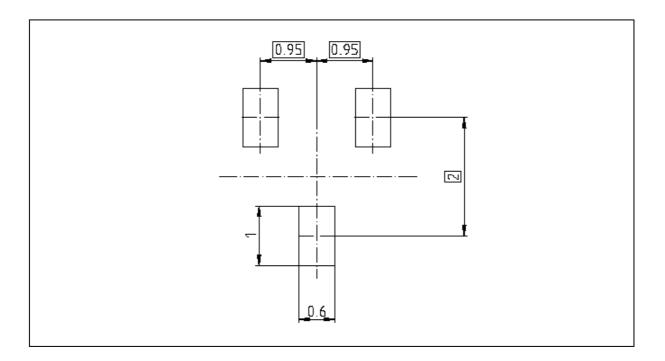


Figure 6: Foot print (SOT-23 compatible)

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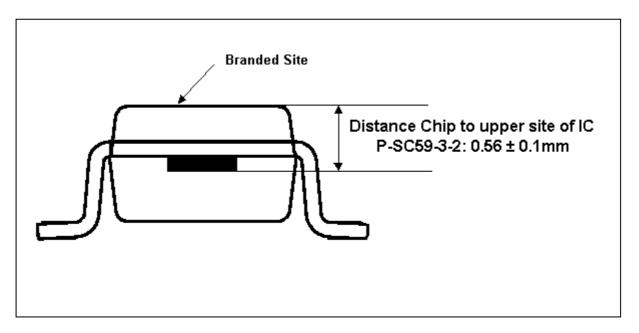


Figure 7: Distance from Package to Die

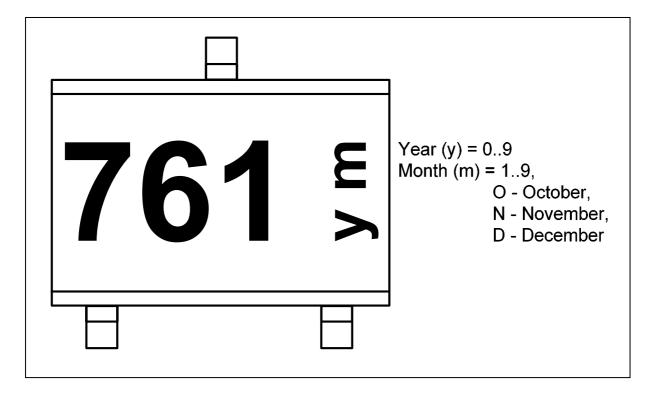


Figure 8: Marking



TLE4976-1F	l	
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Page	Subjects (major changes since last revision)	

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